

REMARKS

Reconsideration of the application is requested.

Claims 16-18 remain in the application. Claims 16-18 are subject to examination.

Under the heading "Claim Rejections – 35 USC § 102" on page 2 of the above-identified Office Action, claims 16-18 have been rejected as being fully anticipated by International Publication WO 02/075815 A1 to Cambou et al., which has been translated into English in Published U.S. Patent Application No. 2004/0080658 A1 under 35 U.S.C. § 102. Applicants respectfully traverse.

The Examiner has alleged that the elements identified by reference numerals 62, 64, 66, and 68 comprise a housing of a semiconductor element. That is incorrect. The elements identified by reference numerals 62, 64, 66, and 68 are the feet of a wall 48 of an optics unit 46. The feet 62, 64, 66, 68 are supported on the active face 79 of the electronic chip forming the image sensor 42 (paragraph 0025-0027). The optics unit 46 does not house the electronic chip forming the image sensor 42.

Cambou et al. teach a semiconductor element, namely, an image sensor 42 that is an electronic chip (paragraph 0024) and that has an active face 79 (paragraph 0027) including the photosensitive surface 44 and an opposite free

face 102 that is disposed directly on a printed circuit board 100 (paragraph 0031). Bonding wires or electrical connections 106 join metallic areas of the image sensor 42 to electrical conductors of the printed circuit board 100 (paragraph 0032). The electronic chip forming the image sensor 42 does not have a housing.

Claim 16 defines an optical module including, inter alia: a circuit carrier and a semiconductor element disposed in a housing disposed on the circuit carrier.

In contrast to the invention as defined by claim 16, Cambou et al. teach that the electronic chip forming the image sensor 42 is not disposed in a housing.

Cambou et al. teach that the electronic chip forming the image sensor 42 has a free face 102 that is placed directly on the printed circuit board 100 (paragraph 0031).

Claim 16 also specifies that the housing of the semiconductor element, at least in sections thereof, has a support formed thereon; and that the base lens of a lens unit is supported on and in direct contact with the support formed on the housing of the semiconductor element.

In contrast to the invention as defined by claim 16, Cambou et al. teach that the optics unit 46 has a wall 48 with feet 62, 64, 66, 68 that are in direct contact with the active face 79 of the electronic chip forming the image sensor 42. The

feet 62, 64, 66, 68 are not supported on nor are they in direct contact with a housing of the electronic chip forming the image sensor 42.

Also in contrast to the invention as defined by claim 16, Cambou et al. teach another embodiment based on a flip-chip design in which the active face 79 of the electronic chip forming the image sensor 42 is directly electrically and mechanically connected to the printed circuit board 100 (See paragraph 0034). There is not a housing.

It is accordingly believed to be clear that none of the references, whether taken alone or in any combination, either show or suggest the features of claim 16. Claim 16 is, therefore, believed to be patentable over the art. The dependent claims are believed to be patentable as well because they all are ultimately dependent on claim 16.

In view of the foregoing, reconsideration and allowance of claims 16-18 are solicited.

In the event the Examiner should still find any of the claims to be unpatentable, counsel would appreciate receiving a telephone call so that, if possible, patentable language can be worked out.

Please charge any fees that might be due with respect to Sections 1.16 and 1.17 to the Deposit Account of Lerner Greenberg Sterner LLP, No. 12-1099.

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Respectfully submitted,

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